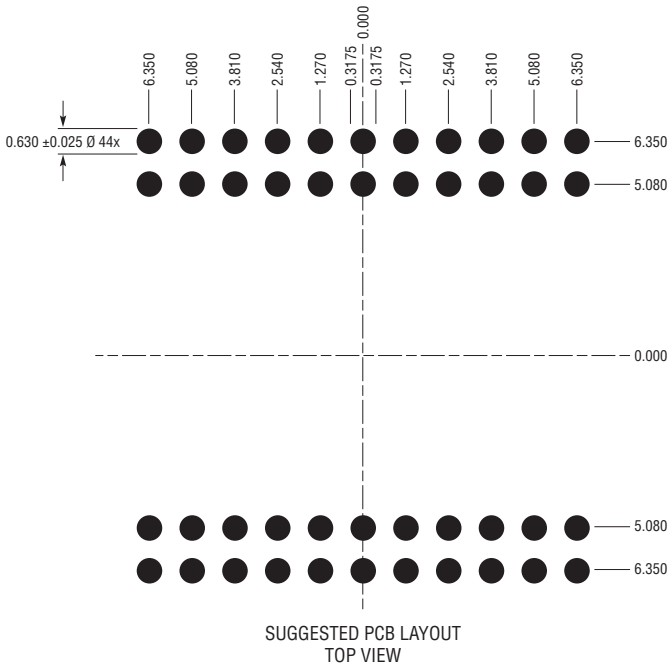
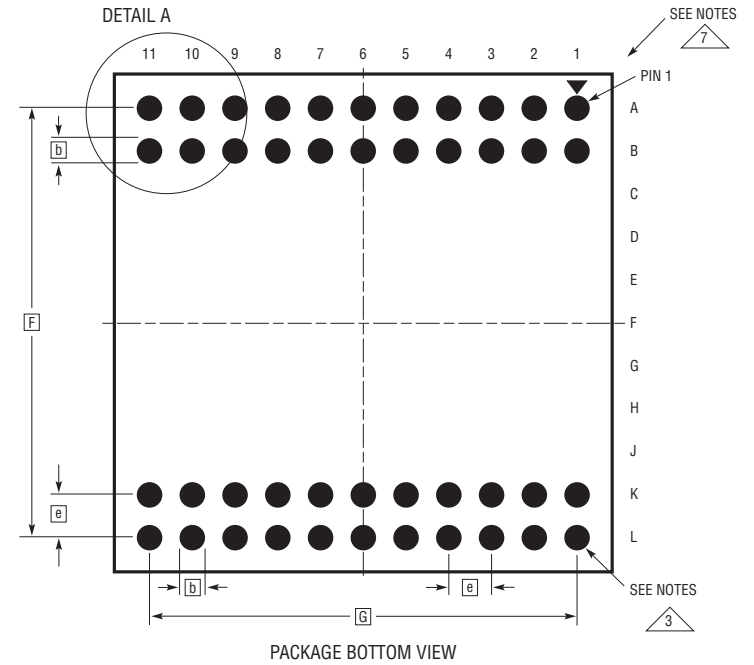
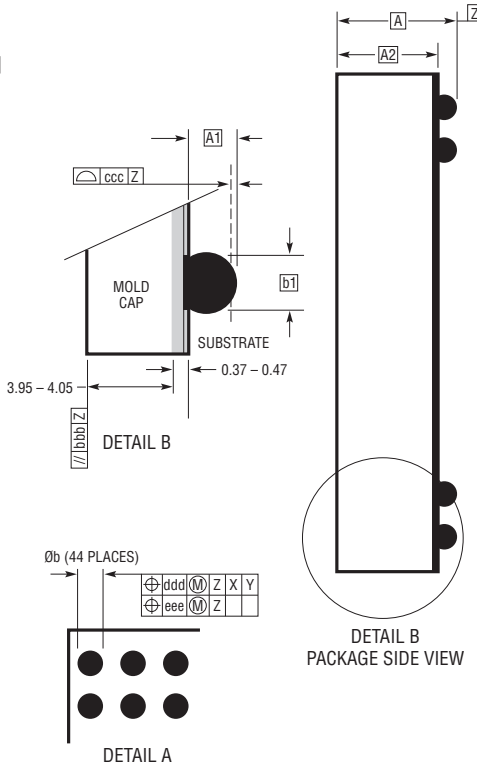
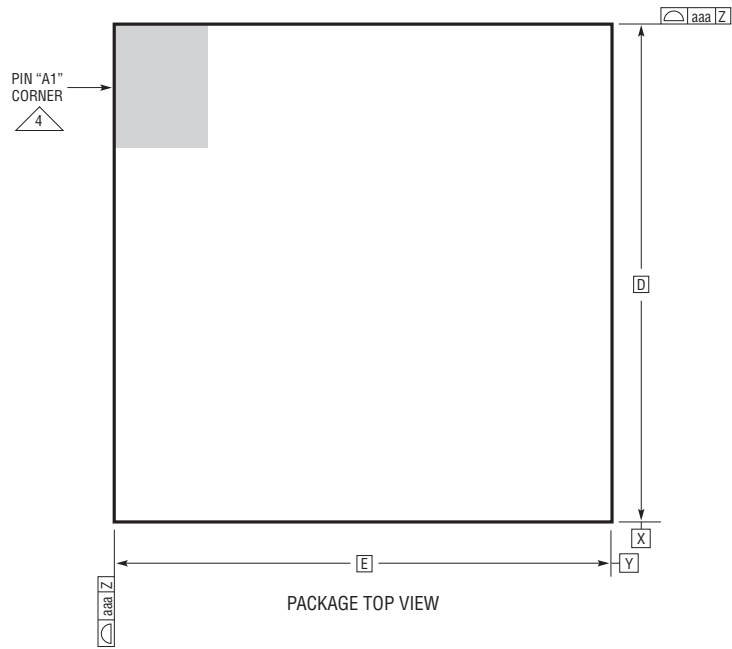


BGA Package
44-Lead (15mm × 15mm × 5.02mm)
 (Reference LTC DWG # 05-08-1881 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.82	5.02	5.22	
A1	0.50	0.60	0.70	
A2	4.32	4.42	4.52	
b	0.71	0.78	0.85	
b1	0.60	0.63	0.66	
D		15.0		
E		15.0		
e		1.27		
F		12.70		
G		12.70		
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 44

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - ALL DIMENSIONS ARE IN MILLIMETERS
 - BALL DESIGNATION PER JESD MS-028 AND JEP95
 - DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 - PRIMARY DATUM -Z- IS SEATING PLANE
 - SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
 - PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

